

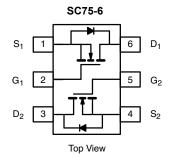
Dual N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)		
60	1.50 at V _{GS} = 4.5V	0.18	0.6		
	1.20 at V _{GS} = 10V	0.20	0.0		

FEATURES

- TrenchFET[®] Power MOSFET
- 100 % R_g Tested
- Gate-Source ESD Protected: 1000 V





APPLICATIONS

- Load/Power Switching for Portable Devices
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Power Supply Converter Circuits

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	60	v		
Gate-Source Voltage		V_{GS}	±20			
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 25 °C	l _D	0.20 ^{a, b}			
Continuous Diain Current (1) = 130 C)	T _A = 70 °C	טי	0.40 ^{a, b}	Α		
Pulsed Drain Current		I _{DM}	2			
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	0.18 ^{a, b}	Α		
Maximum Dawar Dissipations	T _A = 25 °C	P _D	0.22 ^{a, b}	W		
Maximum Power Dissipation ^a	T _A = 70 °C	טי	0.14 ^{a, b}			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Тур.	Max.	Unit
Maximum Junction-to-Ambient ^b	t ≤ 5 s	R _{thJA}	470	565	°C/W
iviaximum Junction-to-Ambient	Steady State	' 'thJA	560	675	J/ VV

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 5 s.

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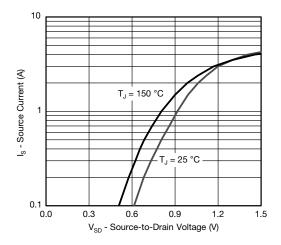
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static						l	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			17			
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$	I _D = 250 μA		- 1.8		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0		2.5	V	
Cata Cauraa Laakaaa	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 30		
Gate-Source Leakage		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			± 1	1	
Zawa Cata Valtana Busin Commant		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$			1	<u>μ</u> Α	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V, T _J = 85 °C			3		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	2			Α	
		$V_{GS} = 4.5 \text{ V}, I_D = 0.18 \text{ A}$		1.5		_	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 0.2 A		1.2		Ω	
Forward Transconductance	9 _{fs}	$V_{DS} = 10 \text{ V}, I_D = 0.2 \text{ A}$		7.5	•	S	
Dynamic ^b							
Input Capacitance	C _{iss}			31		pF	
Output Capacitance	C _{oss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz		10			
Reverse Transfer Capacitance	C _{rss}	30 00		8		1	
Tatal Oats Observe	Q _g	$V_{DS} = 10 \text{ V}, V_{GS} = 8 \text{ V}, I_{D} = 0.2 \text{ A}$			2		
Total Gate Charge				0.75	1.2		
Gate-Source Charge	Q _{as}	Q_{gs} $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 0.2 \text{ A}$		0.15		nC	
Gate-Drain Charge	Q _{gd}			0.13		1	
Gate Resistance	R _g	f = 1 MHz	2.4	12.2	24.4	Ω	
Turn-On Delay Time	t _{d(on)}			11	20		
Rise Time	t _r	$V_{DD} = 10 \text{ V}, R_{L} = 20 \Omega$		16	24		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 0.2 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		26	39	ns	
Fall Time	t _f	-		11	20	1	
Drain-Source Body Diode Characterist	ics		!			l	
Pulse Diode Forward Current ^a	I _{SM}				2	Α	
Body Diode Voltage	V _{SD}	I _S = 0.5 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	-		10	15	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 0 E A 41/35 400 A/35		2	4	nC	
Reverse Recovery Fall Time	t _a	$I_F = 0.5 \text{ A, dI/dt} = 100 \text{ A/}\mu\text{s}$		5		ns	
Reverse Recovery Rise Time	t _b						

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

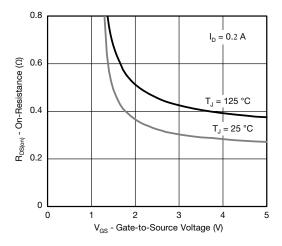
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



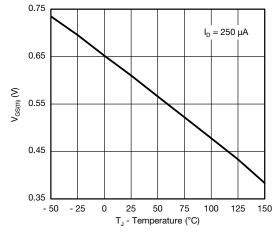
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



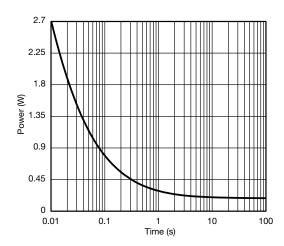
Soure-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



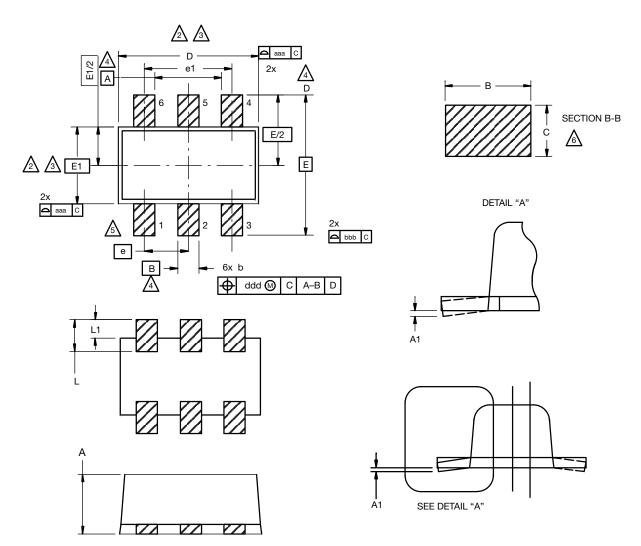
Threshold Voltage



Single Pulse Power, Junction-to-Ambient



SC75-6



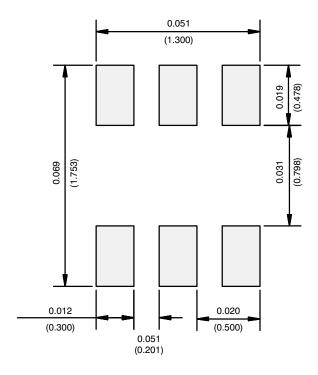
Notes

- 1. Dimensions in millimeters.
- Dimension D does not include mold flash, protrusions or gate burrs. Mold flush, protrusions or gate burrs shall not exceed 0.15 mm per dimension E1 does not include interlead flash or protrusion, interlead flash or protrusion shall not exceed 0.15 mm per side.
- 3. Dimensions D and E1 are determined at the outmost extremes of the plastic body exclusive of mold flash, the bar burrs, gate burrs and interlead flash, but including any mismatch between the top and the bottom of the plastic body.
- 4. Datums A, B and D to be determined 0.10 mm from the lead tip.
- 5. Terminal numbers are shown for reference only.
- These dimensions apply to the flat section of the lead between 0.08 mm and 0.15 mm from the lead tip.

DIM.	MILLIMETERS				
	MIN.	NOM.	MAX.		
Α	0.56	0.58	0.60		
A1	0	0.02	0.10		
b	0.15	0.22	0.30		
С	0.10	0.14	0.18		
D	1.50	1.60	1.70		
Ш	1.50	1.60	1.70		
E1	1.15	1.20	1.25		
e	0.45	0.50	0.55		
e1	0.95	1.00	1.05		
L	0.25	0.35	0.50		
L1	0.10	0.20	0.30		



RECOMMENDED MINIMUM PADS FOR SC75-6



Recommended Minimum Pads Dimensions in Inches/(mm)



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